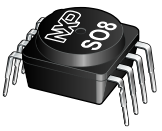


SOT1845-1

SO8, plastic, small outline package; 8 terminals; 2.54 mm pitch; 10.67 mm x 10.67 mm x 5.46 mm body

9 March 2020

Package information

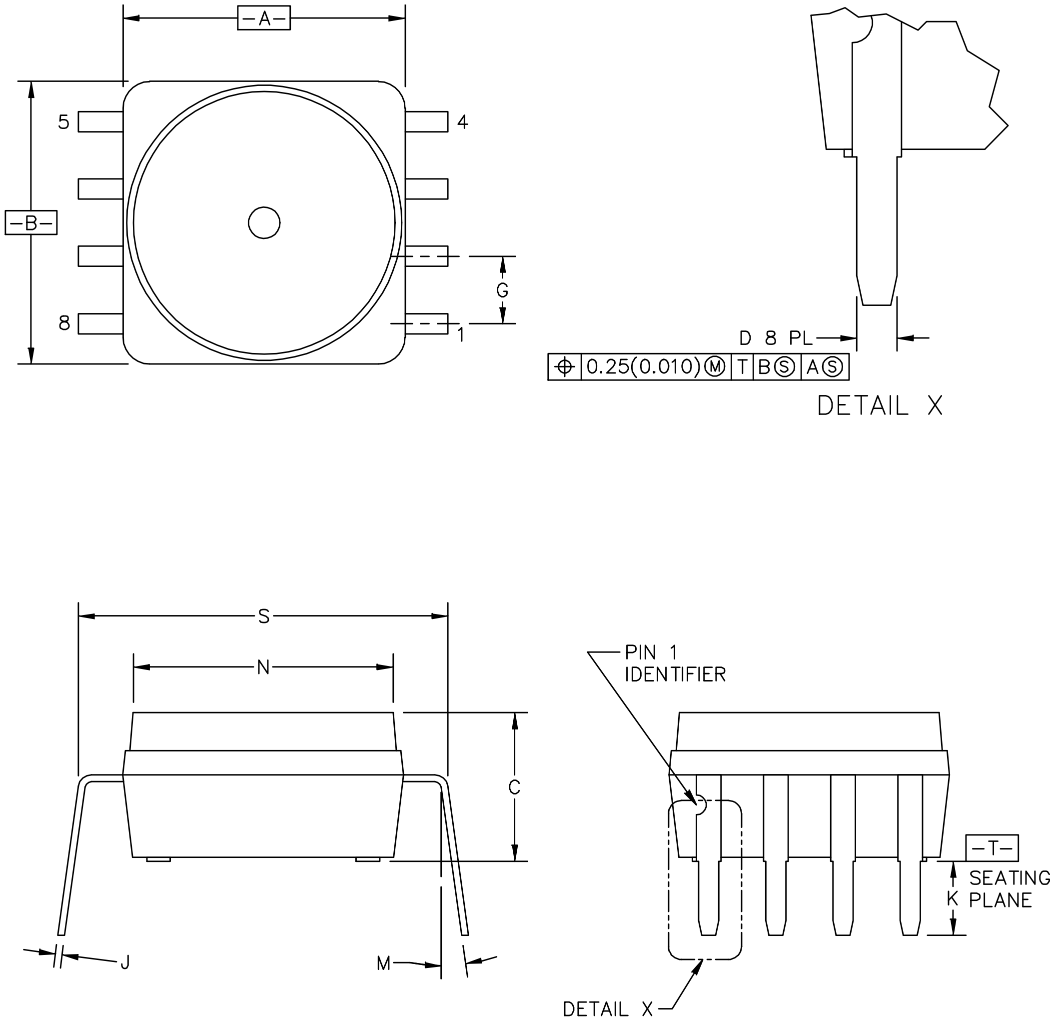
1 Package summary

Terminal position code	D (double)
Package type descriptive code	SO8
Package style descriptive code	SO (small outline)
Package body material type	P (plastic)
Mounting method type	T (through-hole mount)
Issue date	13-02-2020
Manufacturer package code	98ASB17758C

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	10.54	10.67	10.79	mm
package width	10.54	10.67	10.79	mm
package height	5.33	5.46	5.59	mm
nominal pitch	-	2.54	-	mm
actual quantity of termination	-	8	-	

2 Package outline



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TITLE: SENSOR UNIBODY, 10.665 X 10.665 X 5.46 PKG, 2.54 PITCH, 8 I/O	DOCUMENT NO: 98ASB17758C	REV: C
	STANDARD: NON-JEDEC	
	SOT1845–1	13 FEB 2020

Figure 1. Package outline SO8 (SOT1845-1)

NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M–1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION 'A' AND 'B' DO NOT INCLUDE MOLD PROTUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006).
5. ALL VERTICAL SURFACES 5° TYPICAL DRAFT.
6. DIMENSION 'S' TO CENTER OF LEAD WHEN FORMED PARALLEL.
7. 482B–01 AND –02 OBSOLETE. NEW STANDARD 482B–03.

	MILLIMETERS		INCHES		
DIM	MIN	MAX	MIN	MAX	
A	10.54	10.79	0.415	0.425	
B	10.54	10.79	0.415	0.425	
C	5.33	5.59	0.210	0.220	
D	0.66	0.864	0.026	0.034	
G	2.54	BSC	0.100	BSC	
J	0.23	0.28	0.009	0.011	
K	2.54	3.05	0.100	0.120	
M	0°	15°	0°	15°	
N	10.29	10.54	0.405	0.415	
S	13.72	14.22	0.540	0.560	

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	STANDARD: NON–JEDEC	
	SOT1845–1	13 FEB 2020

Figure 2. Package outline nte SO8 (SOT1845-1)

3 Legal information

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